

# 100% Material Declaration Data Sheet FG676 Package for Spartan-6 FPGAs

**Average Weight: 3.0820g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.074896</b>	<b>2.430</b>
	Silicon	7440-21-3	100.00		0.074896	
<b>Die Attach Material</b>					<b>0.013303</b>	<b>0.432</b>
	Silver	7440-22-4	77.50		0.010310	
	Bismaleimide Monomer	Trade Secret	15.00		0.001995	
	Acrylate Monomer	Trade Secret	7.50		0.000998	
<b>Mold Compound</b>					<b>1.387604</b>	<b>45.023</b>
	Solid Epoxy Resin	Trade Secret	5.00		0.069380	
	Phenol Resin	Trade Secret	5.00		0.069380	
	Fused Silica	60676-86-0	87.45		1.213460	
	Metal Hydroxide	Trade Secret	2.00		0.027752	
	Carbon Black	1333-86-4	0.55		0.007632	
<b>Gold Wire</b>					<b>0.018243</b>	<b>0.592</b>
	Gold	7440-57-5	99.05		0.018069	
	Palladium	7440-05-3	0.95		0.000173	
	Calcium	7440-70-2	0.00		0.000000	
<b>Solder Balls</b>					<b>0.665707</b>	<b>21.600</b>
	Tin	7440-31-5	63.00		0.419395	
	Lead	7439-92-1	37.00		0.246312	

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					<b>0.922260</b>	<b>29.924</b>
	Copper	7440-50-8	20.90		0.192724	
	Nickel	7440-02-0	2.11		0.019454	
	Gold	7440-57-5	0.37		0.003423	
Core	Epoxy Resin	Trade Secret	20.31		0.187317	
	Inorganic Filler	21645-51-2	9.12		0.084078	
	Fiberglass	65997-17-3	20.31		0.187317	
	Copper	7440-50-8	3.04		0.028026	
Solder Mask	Talc	14807-96-6	1.02		0.009407	
	Morpholine Derivative	Trade Secret	1.05		0.009684	
	Barium Sulfate	7727-43-7	12.12		0.111759	
	Silica	7631-86-9	0.27		0.002484	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	5.46		0.050382	
	Epoxy Resin	85954-11-6	3.92		0.036193	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/27/10	1.0	Initial Xilinx release.

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.